

40V 3.5mohm N-channel SGT MOSFET SI035N04NG2

Description:

This N channel SGT MOSFET has been designed to low on-state resistance, low switching loss with good EAS performance, especially for DC-DC and Motor driving applications.

Features:

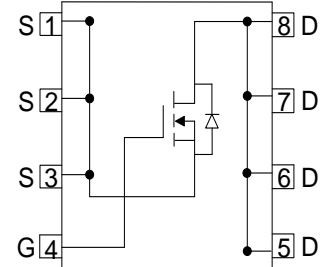
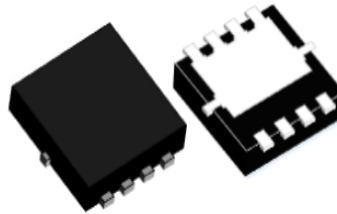
- Low FOM $R_{DS(ON)} \times Q_G$
- Ultra-low on-resistance
- RoHS compliant ^(Note 1)
- Halogen-free ^(Note 1)

Applications:

- Battery management
- Solenoid and Motor Drivers
- DC-DC Converter

Key Performance Parameters:

Parameter	Value	Unit
V_{DS}	40	V
$R_{DS(ON), max} @ V_{GS} = 10V$	3.5	m Ω
I_D	100	A



Ordering Information:

Ordering Code	Package Type	Marking Code	Form	Packing
SI035N04NG2	DFN5X6	SI035N04NG2	Tape Reel	5000PCS

Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Units
V _{DS}	Drain-Source Voltage	40	V
I _D	Drain Current - Continuous (T _C = 25°C) ^(Note 1)	100	A
	Drain Current - Continuous (T _C = 100°C)	68	A
I _{DM}	Drain Current - Pulsed ^(Note 2)	400	A
V _{GS}	Gate-Source Voltage	± 20	V
E _{AS}	Single Pulsed Avalanche Energy ^(Note 3)	110	mJ
P _D	Power Dissipation (T _C = 25°C)	67	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJC}	Thermal Resistance, Junction-to-Case, Steady-State	1.85	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient, Steady State ^(Note 4)	52	°C/W

Notes:

1. The max drain current rating is package limited
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. L = 0.5 mH, V_{DD} = 50V, I_{AS} = 21 A, R_G = 25 Ω, Starting T_J = 25 °C
4. Mount on minimum PCB layout

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V},$			1	μA
I_{GSS}	Gate Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$			± 100	nA
$V_{GS(TH)}$	Gate Threshold voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1	1.7	2.5	V
$R_{DS(ON)}$	Drain-Source on-state resistance	$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		3	3.5	m Ω
		$V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$		3.5	5.0	m Ω
Dynamic Characteristics						
C_{ISS}	Input Capacitance	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V},$ $F = 1\text{ MHz}$		1850		pF
C_{OSS}	Output Capacitance			608		pF
C_{RSS}	Reverse Transfer Capacitance			29		pF
R_G	Gate Resistance	$F = 1\text{ MHz}$		7.2		Ω
Switching Characteristics						
$T_{D(ON)}$	Turn On Delay Time	$V_{DD} = 20\text{ V}, R_L = 1\ \Omega,$ $V_{GS} = 10\text{ V}, R_G = 6\ \Omega$		9		nS
T_R	Rise Time			51		nS
$T_{D(OFF)}$	Turn Off Delay Time			45.5		nS
T_F	Fall Time			78		nS
Q_G	Total Gate Charge	$V_{DD} = 20\text{ V}, I_D = 20\text{ A},$ $V_{GS} = 10\text{ V}$		28.2		nC
Q_{GS}	Gate-Source Charge			4.6		nC
Q_{GD}	Gate-Drain Charge			5.9		nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Body-Diode Forward Current				100	A
I_{SM}	Maximum Pulsed Body-Diode Forward Current ^(NOTE 1)				400	A
V_{SD}	Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 1\text{ A}$		0.7	1	V
T_{RR}	Reverse recovery time	$V_{DD} = 20\text{ V}, I_D = 15\text{ A},$ $di/dt = 100\text{ A}/\mu\text{S}$		40		ns
Q_{RR}	Reverse recovery charge			27		nC
I_{RRM}	Peak Reverse Recovery Current			1.1		A

Electrical Characteristics Diagrams

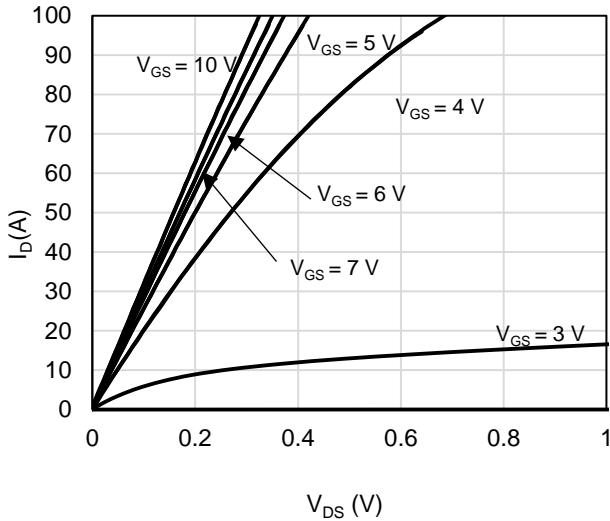


Figure 1: On-Region Characteristics

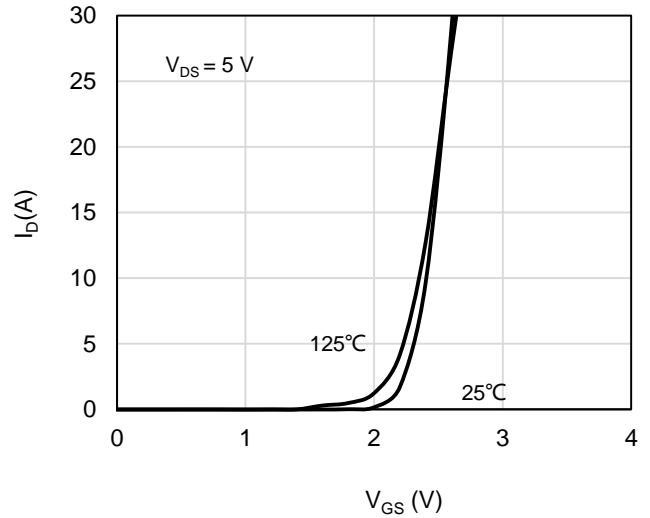


Figure 2: Transfer Characteristics

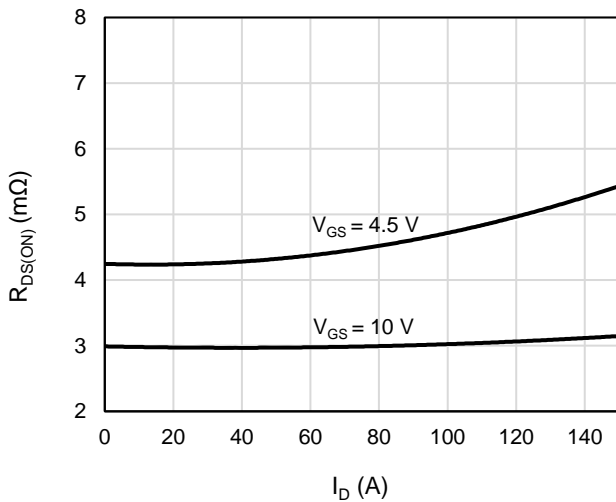


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

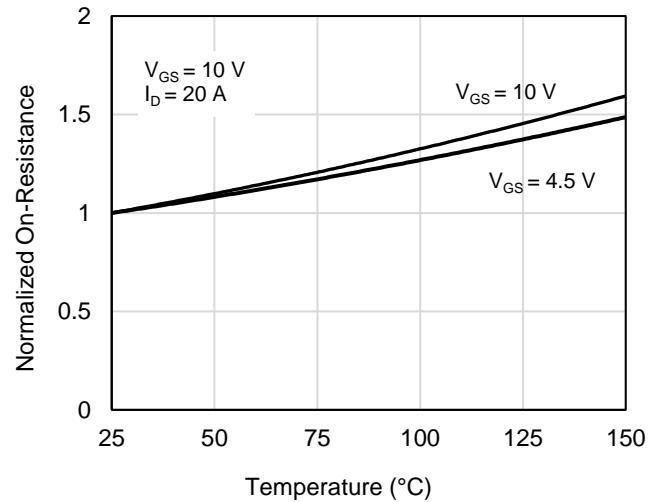


Figure 4: On-Resistance vs. Junction Temperature

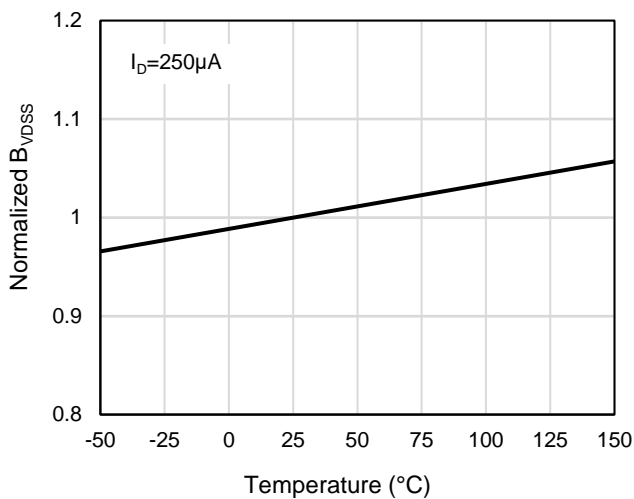


Figure 5: Breakdown Voltage vs. Junction Temperature

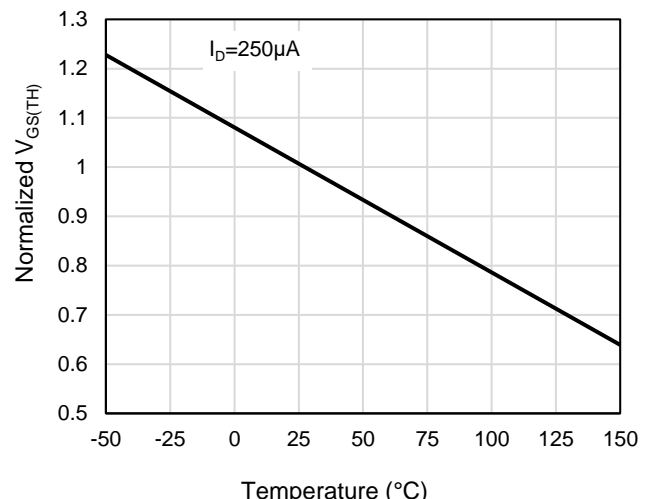


Figure 6: Threshold Voltage vs. Junction Temperature

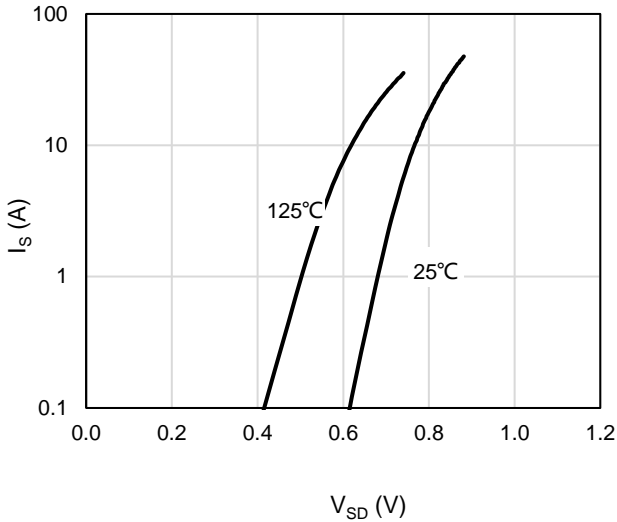


Figure 7: Body-Diode Characteristics

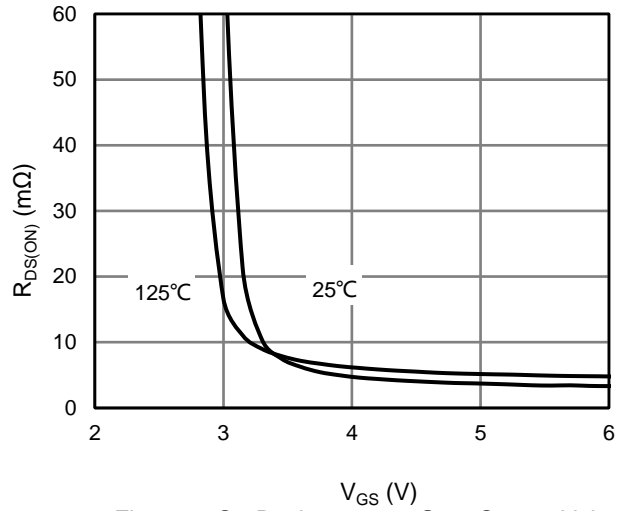


Figure 8: On-Resistance vs. Gate-Source Voltage

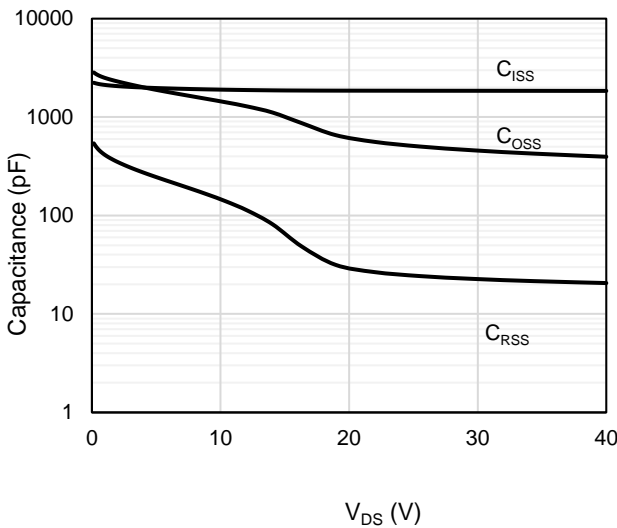


Figure 9: Capacitance Characteristics

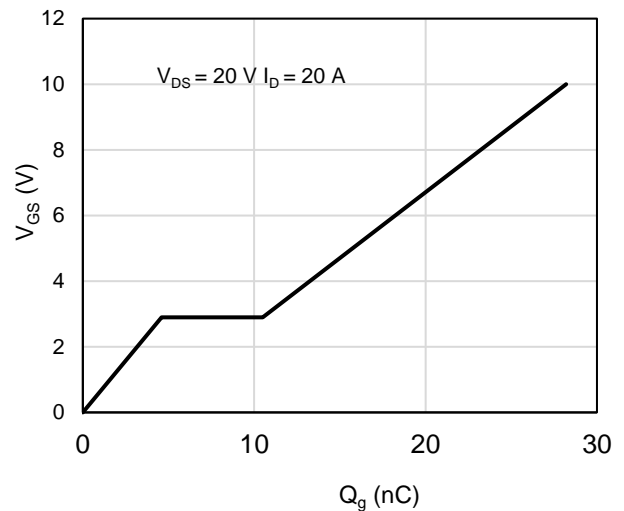


Figure 10: Gate-Charge Characteristics

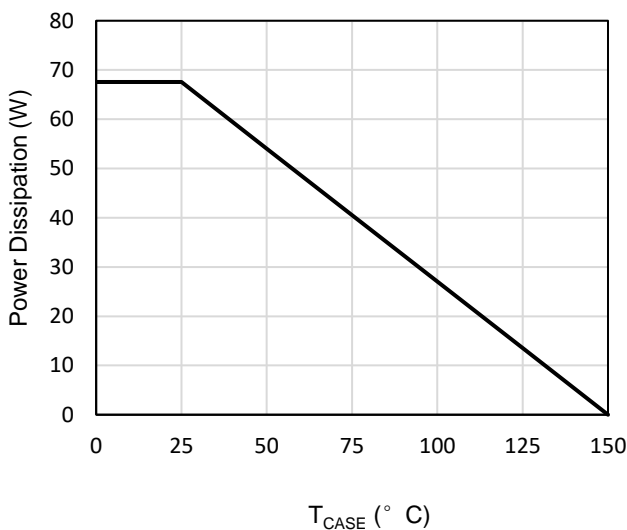


Figure 11: Power De-rating

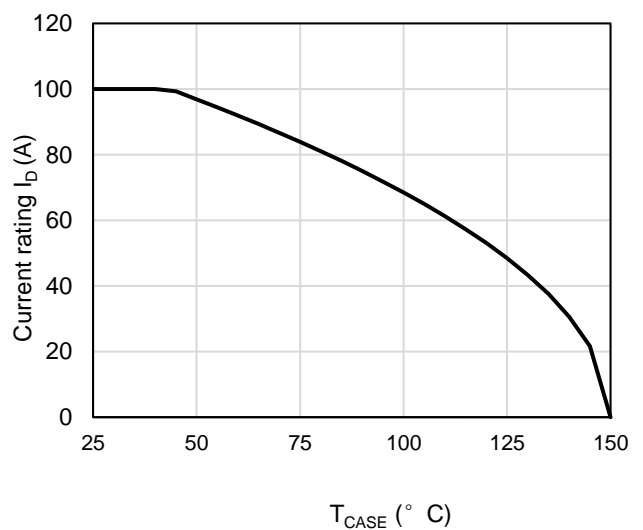
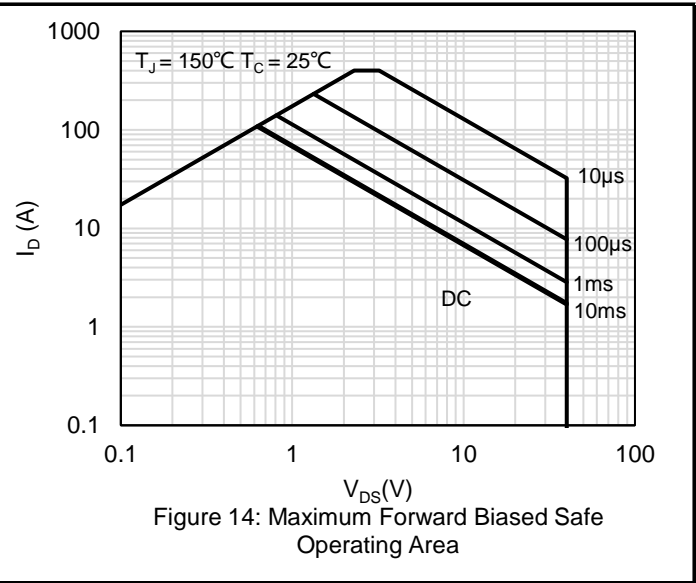
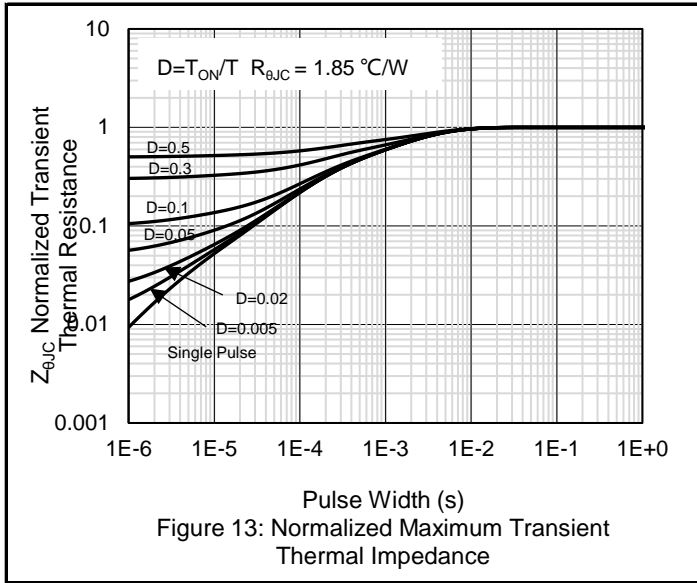
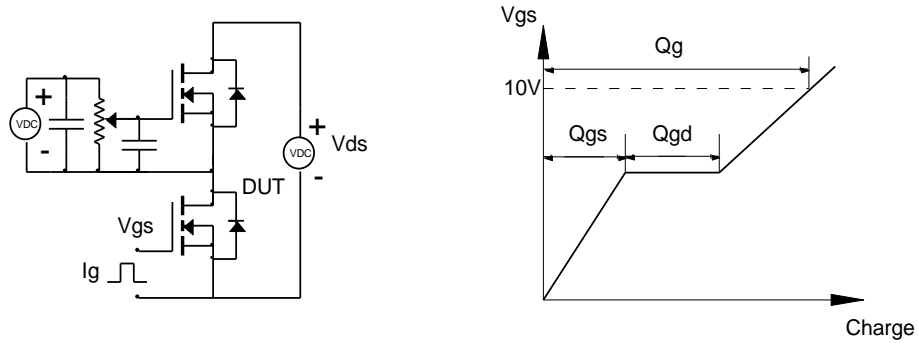


Figure 12: Current De-rating

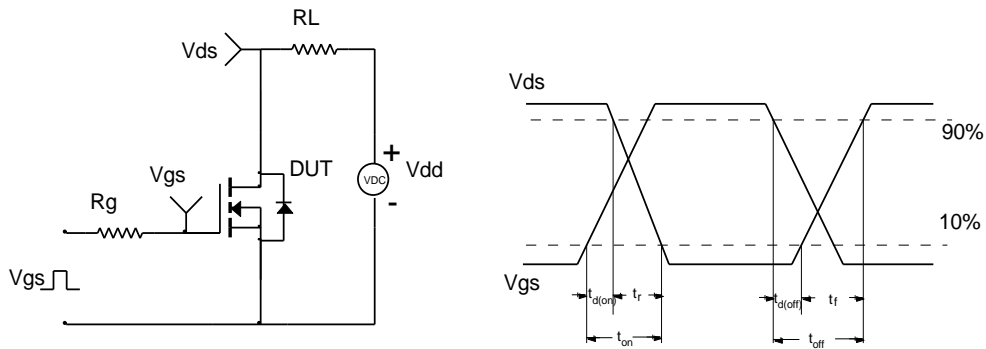


Test Circuit and Waveform

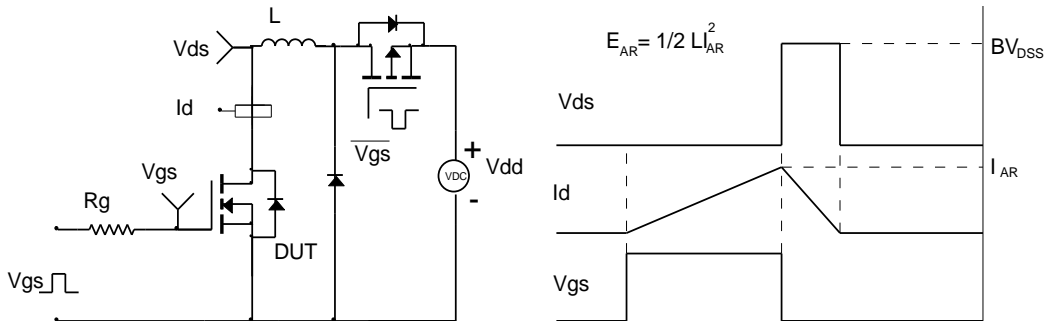
Gate Charge Test Circuit & Waveform



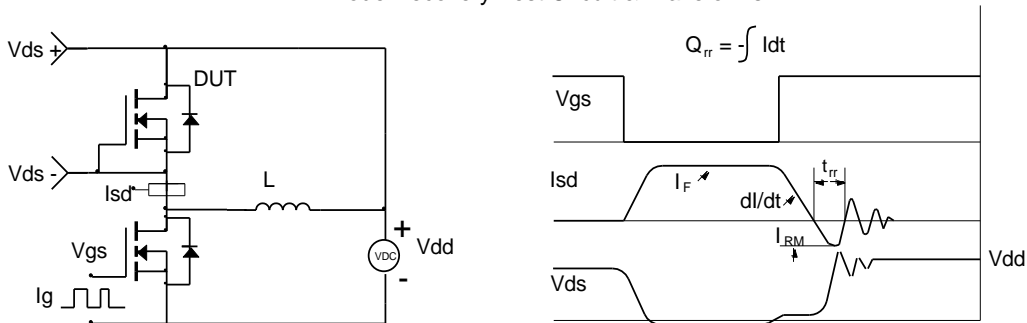
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

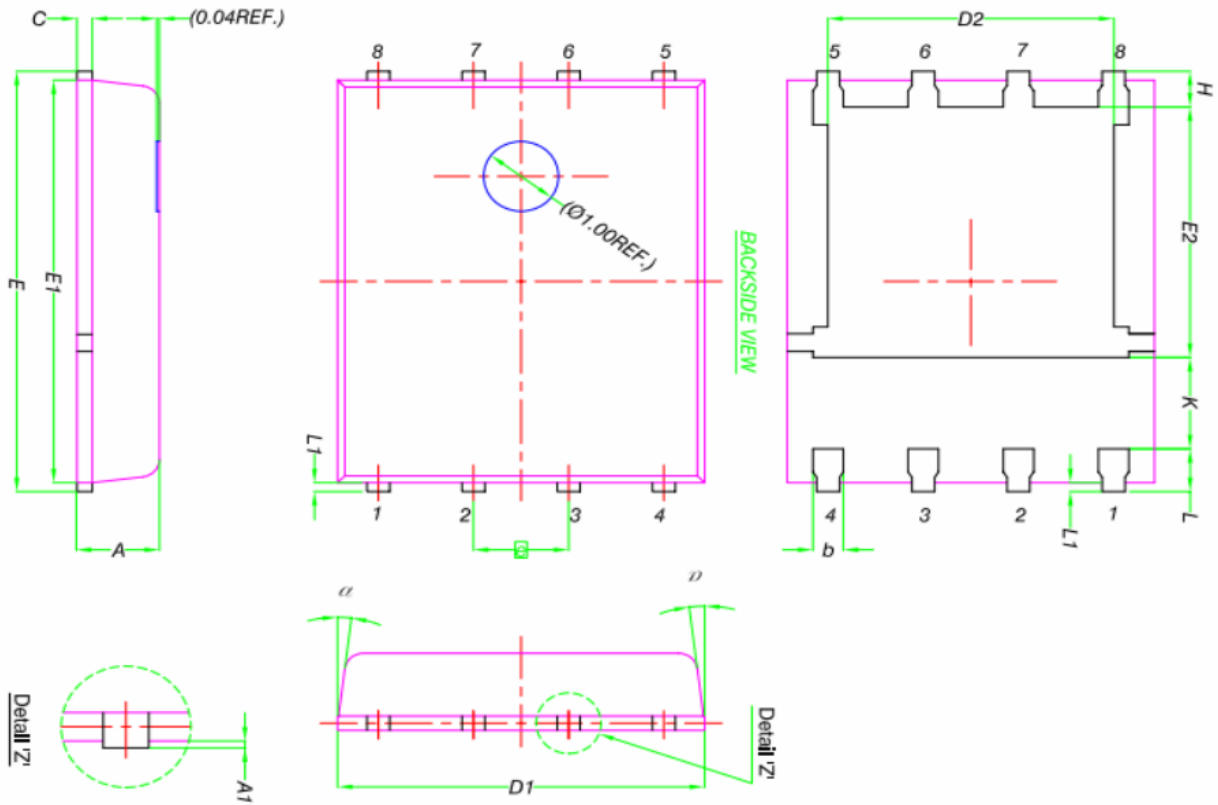


Diode Recovery Test Circuit & Waveforms



Package Outlines

Package Dimensions : PDFN 5*6 PACKAG



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°

